ASSOCIATION CON ELECTRONICS IND	Material Comp © Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute					* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information			
Supplier In	formation														
Company name* Company u				inique ID			Unique ID Authority				Respon	Response Date*			
onsemi											2023-00	2023-06-08			
Contact Name	9	Title - Contact			I	Phone - Contact*				Email -	Email - Contact*				
Product-Env-	Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
uthorized Re	epresentative*	Title - Representative			I	Phone - Representative*				Email -	Email - Representative*				
Product-Env-	-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Red	equester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	ı	Manufacturing Site		Weight*	UOM	Unit Type	
		LC05132C01NMTTT 1 cell LiB I		1 cell LiB Protect	LiB Protection IC		2023-06-08 PHG		HG :		26.64	mg	Each		
Ianufactur	ring Proccess Informa	ation													
Terminal Plating / Grid Array Material To			Perminal Base Alloy J-STD-020 MSI		SL Rating	Peak Proc	Peak Process Body Temperature Max Time at Pea		k Tempera	ture Numb	er of Reflow Cyc	eles			
contains Bi		CU Alloy 3		3		260 C		С	30 seco		nds 3				
omments		•								·	•	•			
TTENTION:	: MSL 3 Rated item requir	es Bake and D	ry Pack (after	electrical test)						·					
or more infor	rmation regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Priective 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.41	mg	Supplier	Silicon (Si)	7440-21-3		2.41	mg
Die Attach Solder	0.89	mg	Supplier	Silver (Ag)	7440-22-4		0.0223	mg
			A	Lead (Pb)	7439-92-1	7a	0.8232	mg
			Supplier	Tin (Sn)	7440-31-5		0.0445	mg
Lead Frame	12.04	mg	Supplier	Silver (Ag)	7440-22-4		0.3612	mg
			Supplier	Tin (Sn)	7440-31-5		0.0181	mg
			Supplier	Copper (Cu)	7440-50-8		11.6607	mg
Mold Compound-Black	10.73	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.073	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0536	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		1.5558	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.9745	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.073	mg
Plating	0.54	mg	В	Bismuth (Bi)	7440-69-9		0.0041	mg
			Supplier	Tin (Sn)	7440-31-5		0.536	mg
Wire Bond - Au	0.03	mg	Supplier	Gold (Au)	7440-57-5		0.03	mg